

# Dual High-Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.58 \text{ V}$  at  $I_F = 2.5 \text{ A}$

## eSMP® Series SMPD (TO-263AC)



## DESIGN SUPPORT TOOLS AVAILABLE



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 5 A
$V_{RRM}$	150 V
$I_{FSM}$	80 A
$V_F$ at $I_F = 5 \text{ A}$ ( $T_A = 125 \text{ °C}$ )	0.68 V
$T_J$ max.	175 °C
Package	SMPD (TO-263AC)
Circuit configuration	Common cathode

## FEATURES

- Trench MOS Schottky technology
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available:
  - Automotive ordering code: base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection in commercial, industrial, and automotive application.

## MECHANICAL DATA

**Case:** SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** as marked

MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V10DM150C	UNIT
Device marking code		V10DM150C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$ (1)	10	A
		5	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	80	A
Operating junction temperature range	$T_J$ (2)	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	

## Notes

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 2.5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.77	-	V
	I <sub>F</sub> = 5 A			1.05	1.15	
	I <sub>F</sub> = 2.5 A	T <sub>A</sub> = 125 °C		0.58	-	
	I <sub>F</sub> = 5 A			0.68	0.76	
Reverse current at rated V <sub>R</sub> per diode	V <sub>R</sub> = 100 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.01	-	mA
		T <sub>A</sub> = 125 °C		1	-	
	V <sub>R</sub> = 150 V	T <sub>A</sub> = 25 °C		-	0.1	
		T <sub>A</sub> = 125 °C		2	4	
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	300	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ 

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	V10DM150C	UNIT
Typical thermal resistance per device	$R_{\theta JC}^{(1)}$	2.7	$^{\circ}\text{C/W}$
	$R_{\theta JA}^{(1)(3)}$	58	

**Notes**

(1) Mounted on infinite heatsink

(2) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  - junction-to-ambient

(3) Free air, without heatsink

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V10DM150C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel
V10DM150CHM3/I <sup>(1)</sup>	0.55	I	2000/reel	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

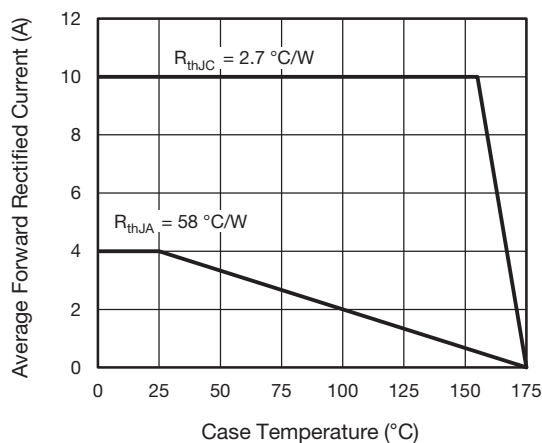
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

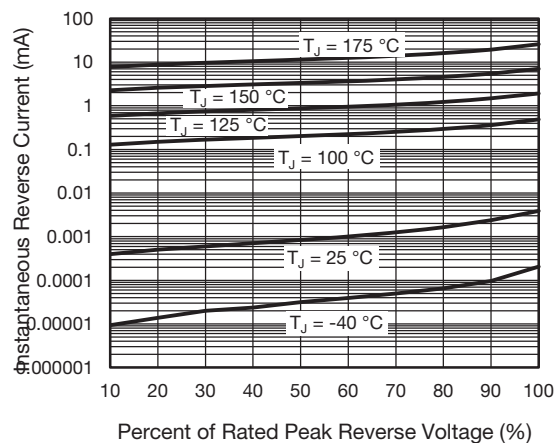


Fig. 4 - Typical Reverse Leakage Characteristics

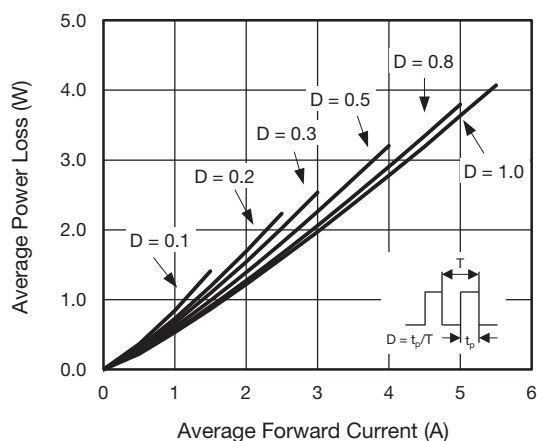


Fig. 2 - Average Power Loss Characteristics

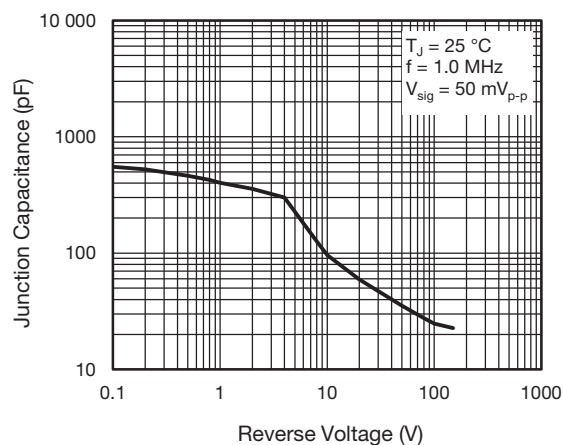


Fig. 5 - Typical Junction Capacitance

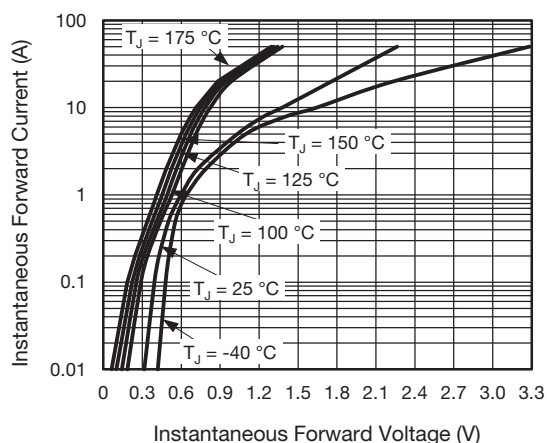


Fig. 3 - Typical Instantaneous Forward Characteristics

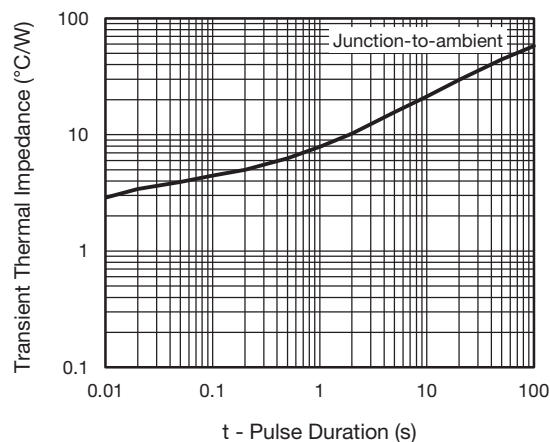


Fig. 6 - Typical Transient Thermal Impedance

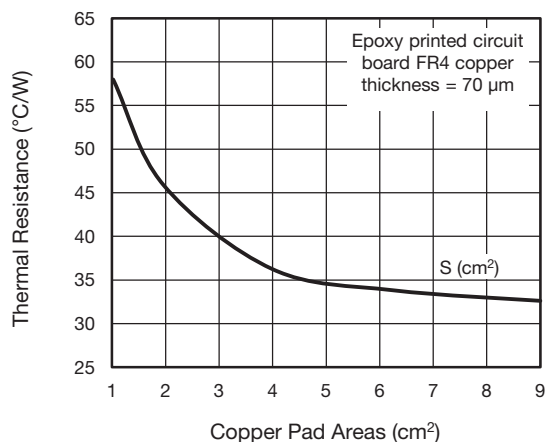
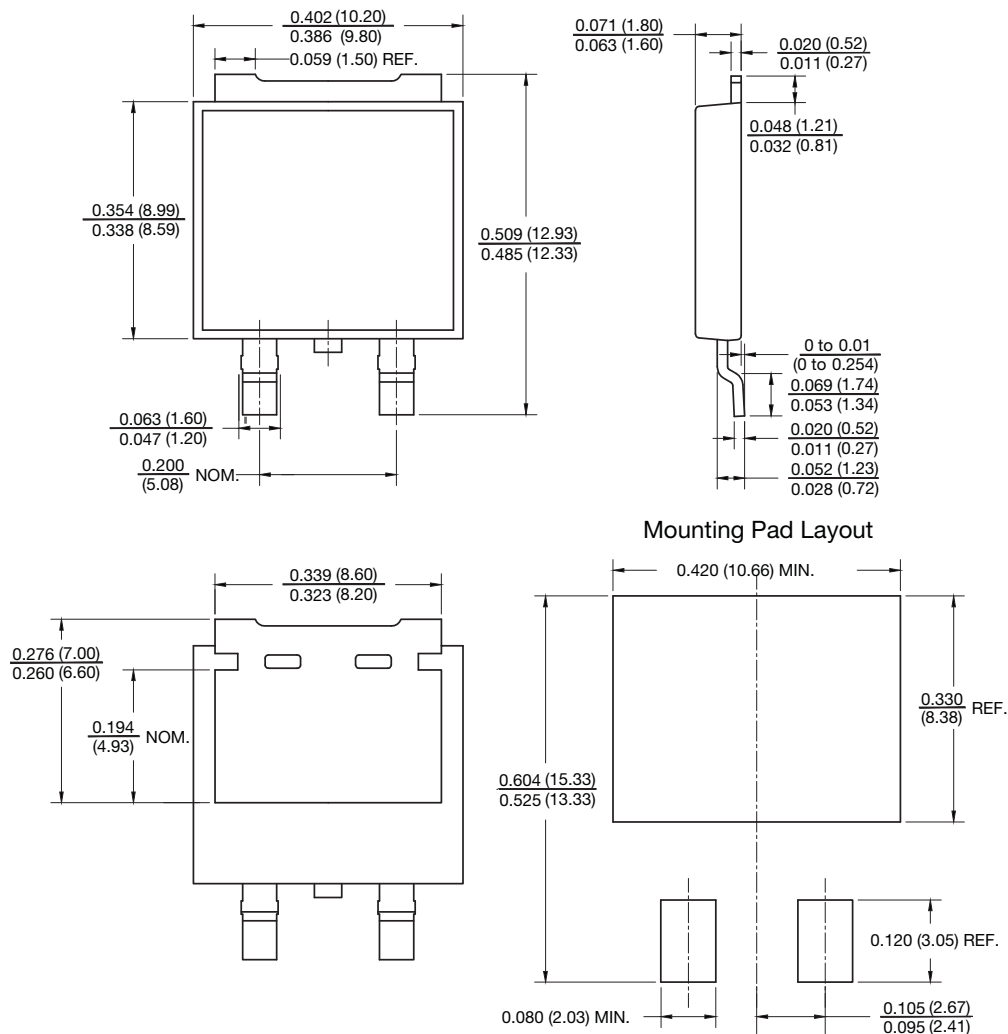


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

#### SMPD (TO-263AC)





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